

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3971idd-3.3#trpbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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**TOTAL MASS (g) : 0.022731**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001215	1000000	53450.3867188		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	427207.15625		
		Iron (Fe)	7439-89-6	0.000239	24000	10514.1083984		
		Phosphorus (P)	7723-14-0	0.000003	300	131.976257324		
		Zinc (Zn)	7440-66-6	0.000007	700	307.944610596		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.009960</b>	<b>1000000</b>	<b>438161.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000455	1000000	20032.3535156		
		<b>External Plating Total:</b>				<b>0.000455</b>	<b>1000000</b>	<b>20032.3535156</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9898.21972656		
<b>Internal Plating Total:</b>				<b>0.000225</b>	<b>1000000</b>	<b>9898.21972656</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000263	800000	11569.9179688		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000066	200000	2903.47753906		
<b>Die Attach Total:</b>				<b>0.000329</b>	<b>1000000</b>	<b>14473.3964844</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001362	130000	59917.21875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.009013	860000	396500.65625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000105	10000	4619.16894531		
		<b>Encapsulation Total:</b>				<b>0.010480</b>	<b>1000000</b>	<b>461037.03125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000067	1000000	2947.46972656		
					<b>TOTAL MASS (g) :</b>	<b>0.022731</b>		